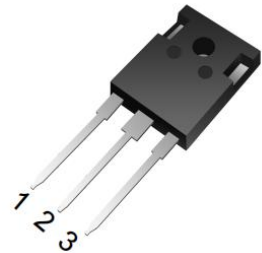
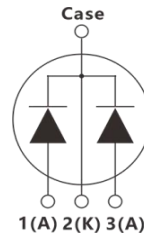


### Silicon Carbide Schottky Diode 650V/30A

Parameter	Value	Unit
$V_{RRM}$	650	V
$I_F$ ( $T_C = 150^\circ\text{C}$ )	30	A
$Q_C$	41	nC



TO-247-3L

### Features

- Zero reverse recovery current
- Zero forward recovery voltage
- Temperature independent switching behavior
- High temperature operation
- High frequency operation

### Applications

- SMPS, PFC
- Solar application, UPS, EV/HEV
- Motor drives, Wind turbine, Rail traction

### Maximum Rated Values (at $T_J = 25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Value	Unit	Test Conditions	Note
Repetitive Peak Reverse Voltage	$V_{RRM}$	650	V		
Surge Peak Reverse Voltage	$V_{RSM}$	650	V		
DC Blocking Voltage	$V_{DC}$	650	V		
Continuous Forward Current (Per Leg/Per Device)	$I_F$	15/30	A	$T_C = 150^\circ\text{C}$	Fig.7
Repetitive Peak Forward Surge Current	$I_{FRM}$	105*	A	$T_C = 25^\circ\text{C}$ , $t_p = 10$ ms, Half Sine Wave	
Non-Repetitive Peak Forward Surge Current	$I_{FSM}$	135*	A	$T_C = 25^\circ\text{C}$ , $t_p = 10$ ms, Half Sine Wave	
Non-Repetitive Peak Forward Surge Current	$I_{F\text{ Max}}$	1200*	A	$T_C = 25^\circ\text{C}$ , $t_p = 10$ $\mu\text{s}$ , Pulse	
Power Dissipation	$P_{tot}$	159* 68*	W	$T_C = 25^\circ\text{C}$ , $T_C = 110^\circ\text{C}$	Fig.6
Operating Junction and Storage Temperature	$T_J, T_{stg}$	-55 to +175	$^\circ\text{C}$		

### Electrical Characteristics (at $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Typ.	Max.	Unit	Test Conditions	Note
Forward Voltage	$V_F$	1.45 1.75	1.8 3.0	V	$I_F=15\text{A}, T_J=25^\circ\text{C}$ $I_F=15\text{A}, T_J=175^\circ\text{C}$	Fig.1
Reverse Current	$I_R$	4 40	20 200	$\mu\text{A}$	$V_R=650\text{V}, T_J=25^\circ\text{C}$ $V_R=650\text{V}, T_J=175^\circ\text{C}$	Fig.2
Total Capacitive Charge	$Q_C$	41		nC	$V_R=400\text{V}, T_J=25^\circ\text{C}$ $Q_C = \int_0^{V_R} C(V)dV$	Fig.4
Total Capacitance	C	860 85 60		pF	$V_R=0\text{V}, T_J=25^\circ\text{C}, f=1\text{MHz}$ $V_R=200\text{V}, T_J=25^\circ\text{C}, f=1\text{MHz}$ $V_R=400\text{V}, T_J=25^\circ\text{C}, f=1\text{MHz}$	Fig.3
Capacitance Stored Energy	$E_C$	8.2		$\mu\text{J}$	$V_R=400\text{V}$	Fig.5

### Thermal Characteristics

Parameter	Symbol	Test Condition	Value			Unit
			min.	typ.	max.	
Thermal Resistance, junction-case	$R_{th(j-c)}$		-	0.94	-	$^\circ\text{C}/\text{W}$

### Typical Characteristics Curves

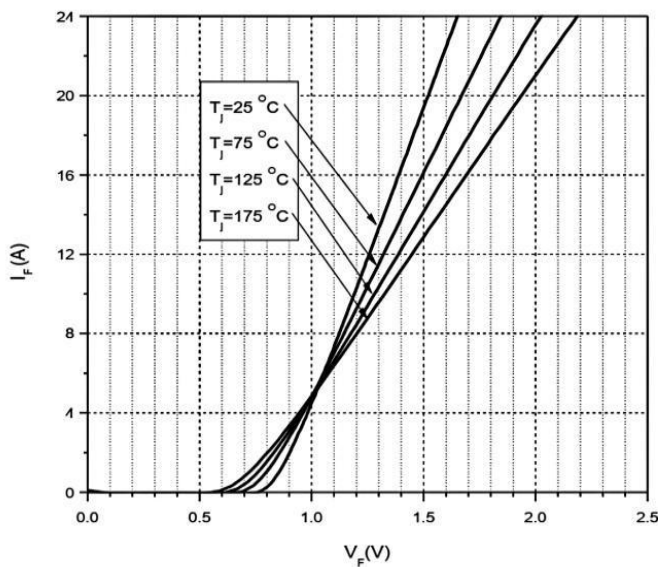


Fig 1. Forward Characteristics

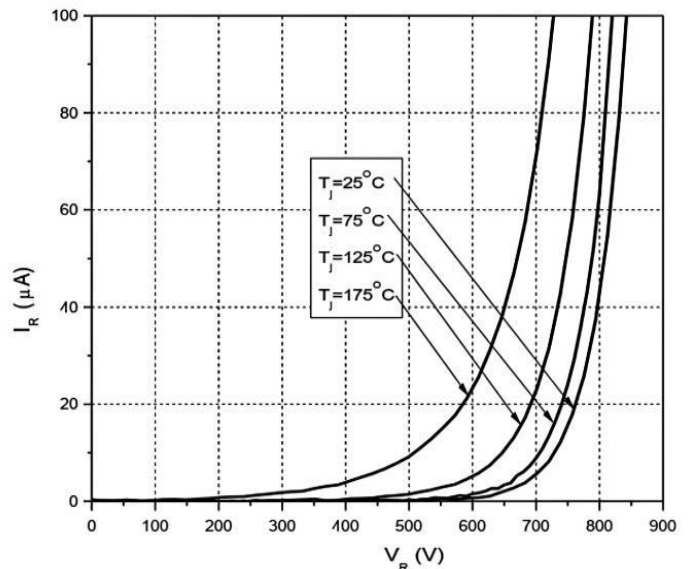


Fig 2. Reverse Characteristics

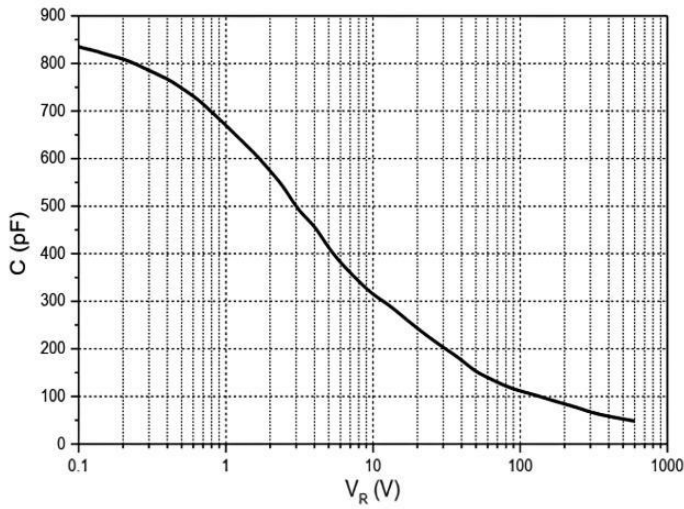


Fig 3.Capacitance vs.Reverse Voltage

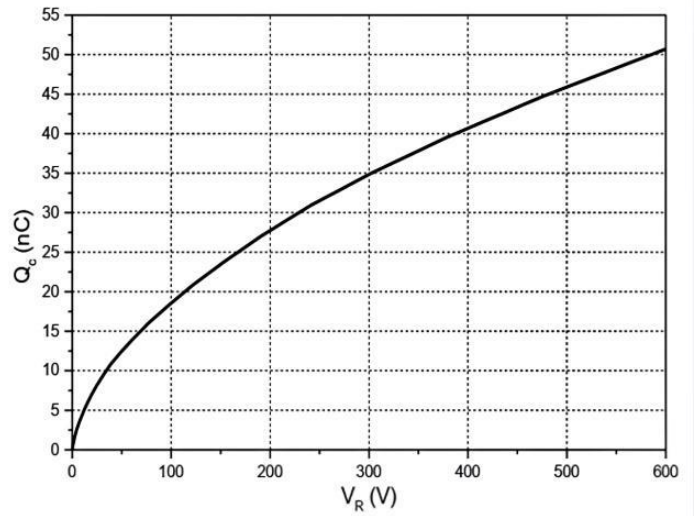


Fig 4.Total Capacitance Charge vs.Reverse Voltage

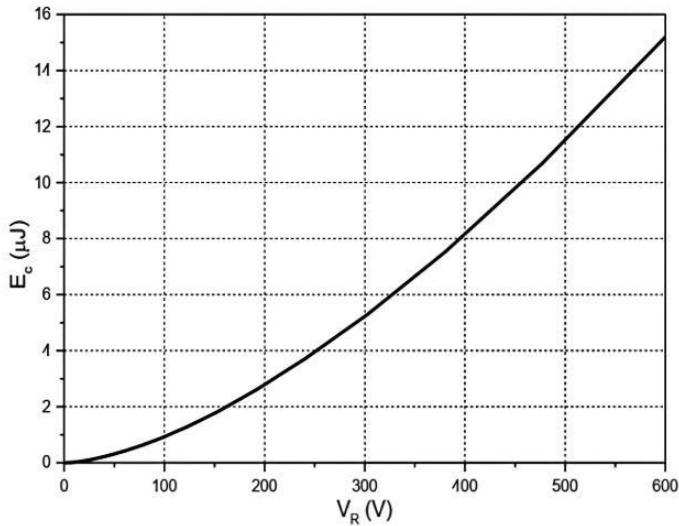
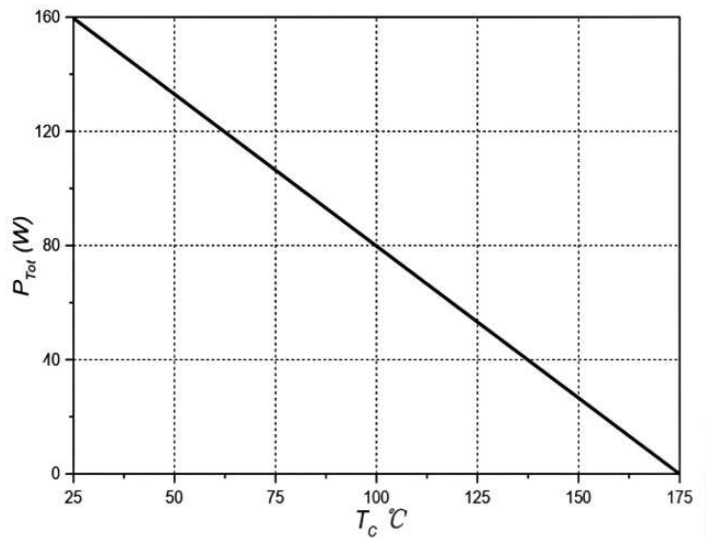


Fig 5.Capacitance Stored Energy Figure



6.Power Derating

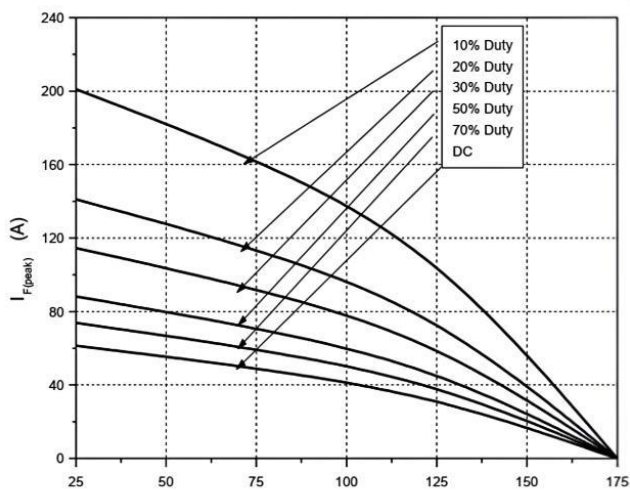


Fig 7.Current Derating

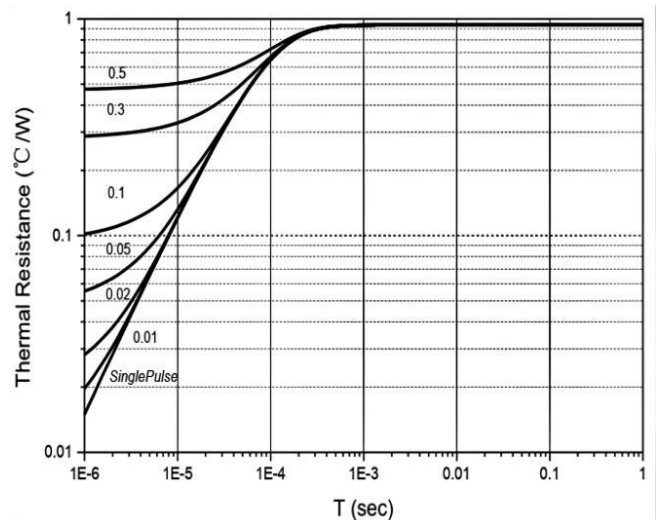
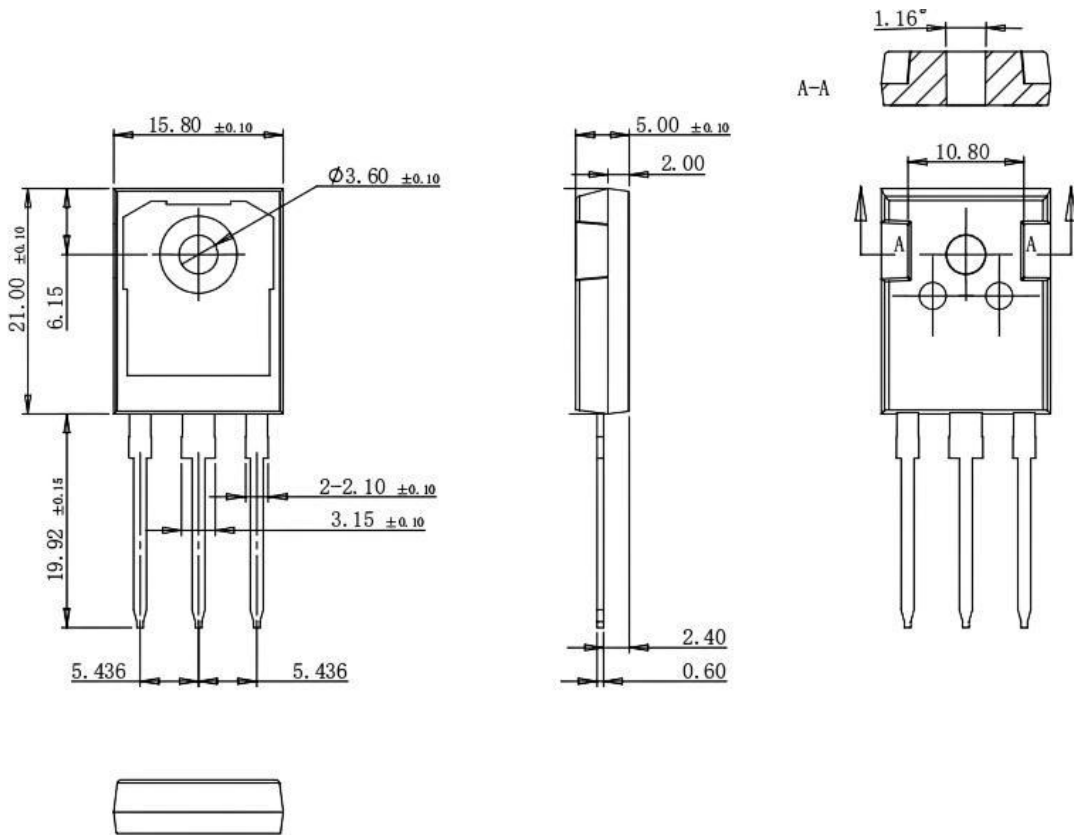


Fig 8.Transient Thermal Impedance

**Package Outlines(Unit: mm)**



**\*Important Usage Information and Disclaimer**

The specifications of Zhuhai Hypersemi Co., Ltd. products are not guarantees of product characteristics. They reflect typical performance expected in standard applications, which may vary with specific uses. Users must conduct prior testing for their applications and make necessary adjustments.

Users are responsible for the safety of applications utilizing our products and must implement adequate safety measures to prevent physical injury, fire, or other risks in case of product failure. It is the user's duty to ensure that application designs comply with all applicable laws and standards. Our products must not be used in any applications where a product failure could reasonably result in personal injury, unless specifically authorized in a signed document by Zhuhai Hypersemi Co., Ltd.

No representations or warranties are made regarding the accuracy or completeness of this information, including any claims of non-infringement of third-party intellectual property rights. Zhuhai Hypersemi Co., Ltd. assumes no liability for any applications or uses of its products and does not grant any licenses to its intellectual property rights or those of others. We also make no claims regarding non-infringement of third-party intellectual property rights that may arise from applications.

Due to technical requirements, our products may contain hazardous substances. For details, please contact your nearest sales office. This document replaces all previous information and may be updated. We reserve the right to make changes.